



Data Sheet AMM-2738-3-B

Features:

The AMM-2738-3-B analog MEMS microphone features a specialized preamplification ASIC that provides high sensitivity and high SNR output from a capacitive audio sensor. It's packaged for surface mounting and high temperature reflow assembly.

- -38dB sensitivity
- 63dB Signal-to-Noise
- Analog output
- Small 2.75mm x 1.85mm surface-mount package
- Anti-RF interference

Specifications ($V_{DD} = 2.7V$, $T_A = 23\pm2^{\circ}C$, RH = $55\pm10\%$, unless otherwise specified.)

Parameter	Test Condition	Value	Unit
Sensitivity	94dBSPL f _{IN} = 1 kHz	-39 (min) -38 (typ) -37 (max)	dB
Supply Voltage		2.0 (typ)	V_{DD}
Supply Voltage Range		1.6 (min) 3.6 (max)	V_{DD}
Output Impedance	$f_{TEST} = 1 kHz$	300 (max)	Ω
Supply Current	$1.6V \le V_{DD} \le 3.6V$	200 (max)	μΑ
Signal-to-Noise Ratio	f _{IN} = 1kHz 94dBSPL A-weighted	63 (typ)	dB
Frequency Range	See Frequency Response Curve for response limits	100 – 20k	Hz
Total Harmonic Distortion	$f_{IN} = 1 \text{ kHz}$ 94dBSPL	0.1 (max)	%
Acoustic Overload Point (AOP)	(f _{TEST} = 1kHz, 10% THD)	124 (typ)	dB
Power Supply Rejection	100mV _{PP} 217 Hz square wave on V _{DD} , A-weighted	-100 (typ)	dB
Power Supply Rejection Ratio	200mV _{PP} 1kHz sinewave on V _{DD} , A-weighted	70 (typ)	dB

Physical Properties

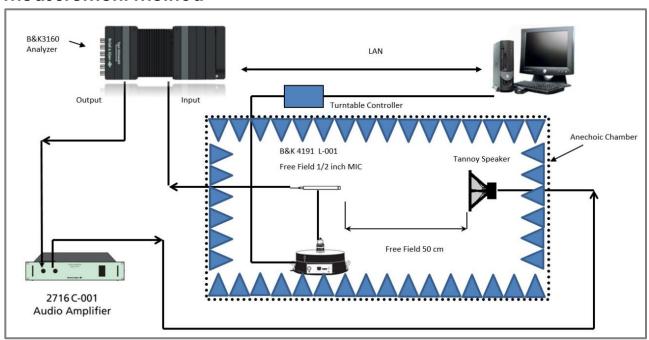
Parameter	Condition	Value	Unit
Directivity		Omnidirectional	
Weight		0.1 (max)	Grams
Operating Temperature		-40 (min) 85 (max)	°C
Storage Temperature		-40 (min) 100 (max)	°C
MSL (Moisture Sensitivity Level)*		Class 1	
Acceptable Soldering Methods		See below for reflow soldering information	
Environmental Compliances		RoHS/Halogen Free	

^{*}MSL level dependent on product remaining in sealed packaging until use

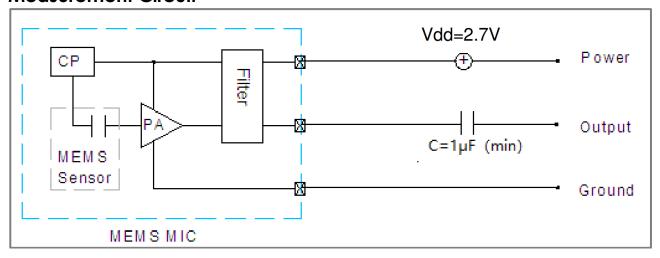
Absolute Maximum Ratings

Parameter	Condition	Value	Unit
Supply Voltage		3.6 (max)	V_{DC}
Voltago on any Pin		-0.3 (min)	V
Voltage on any Pin		$V_{DD} + 0.3$	V
Max Sound Pressure Level		160	dB
Max Mechanical Shock		10000	G
Max Vibration		Pre-MIL-STD-8	83 Method
Max vibration		2007, Test C	ondition B

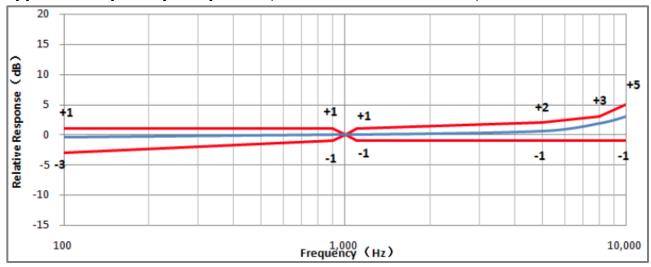
Measurement Method



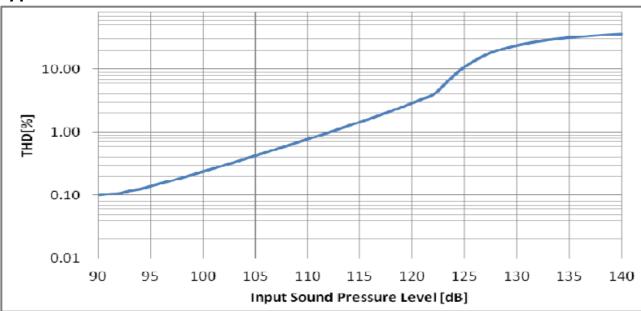
Measurement Circuit



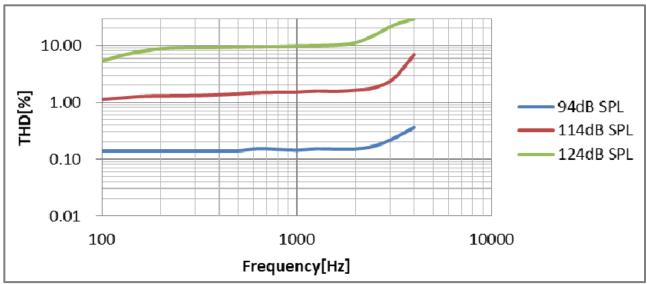
Typical Frequency Response (Normalized to 0dB at 1kHz)



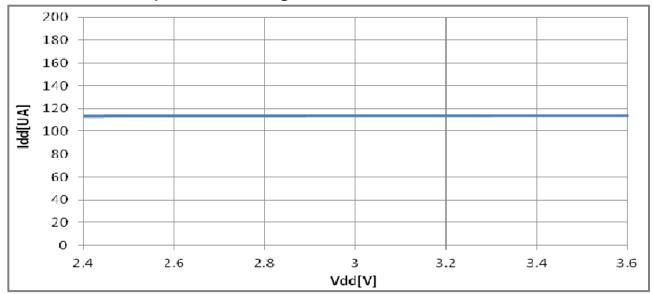
Typical THD Vs SPL



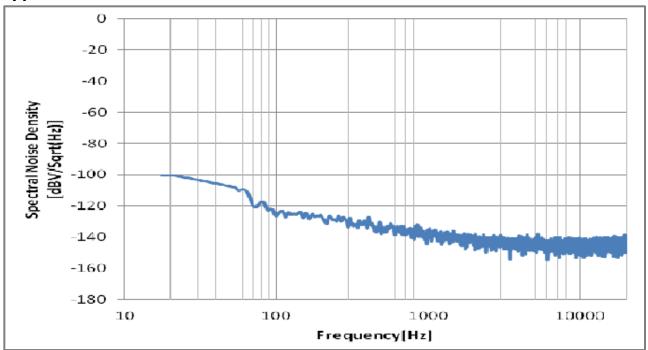
Typical THD Vs Frequency



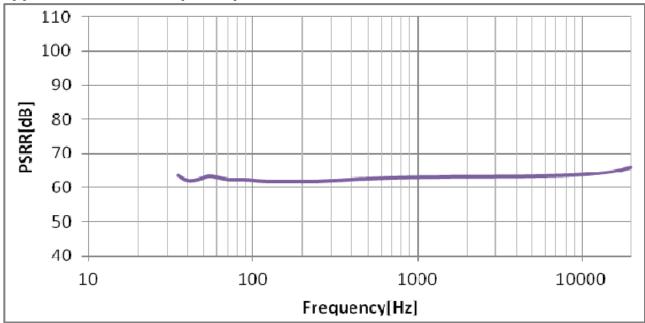
Current Consumption Vs Voltage



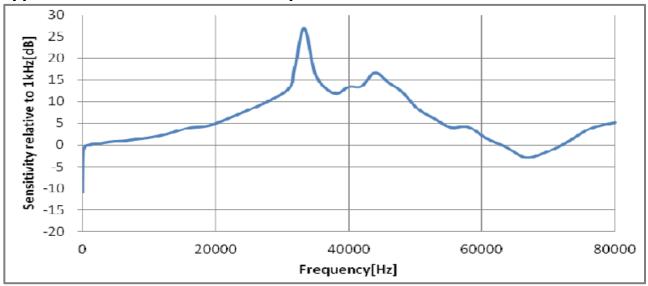
Typical Noise Floor



Typical PSRR Vs Frequency

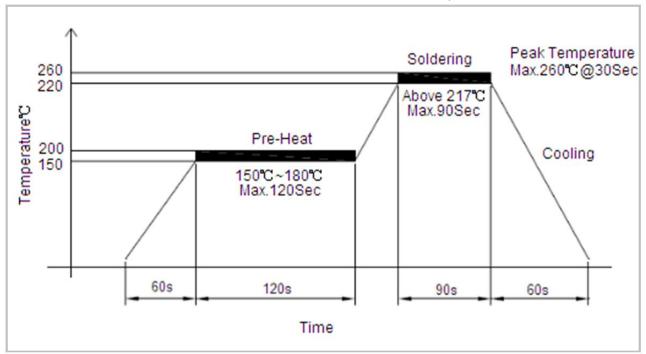


Typical Free Field Ultrasonic Response



Recommended Reflow Soldering Procedure (Recommended profile,

temperature ≤ 260°C, 30s maximum at peak temperature)



Important notes to minimize device damage:

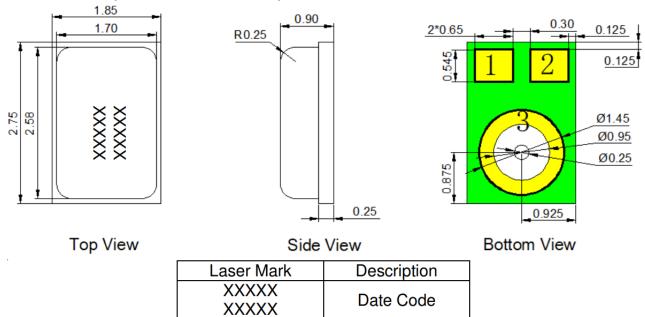
- 1. Do not handle the microphone with pick-and-place vacuum tools that could contact the microphone acoustic port hole.
- 2. Never expose the microphone's acoustic port hole to vacuum. Such exposure can damage or destroy the MEMS element.
- 3. Never allow air to blow air into the microphone acoustic port hole. The port hole must be sealed to prevent particle contamination if a blown air-cleaning process is used,
- 4. A clean room environment is recommended for PCB assembly to avoid microphone contamination.
- 5. Do not use blown air or ultrasonic cleaning procedures on MEMS Microphones. A noclean paste is recommended for the assembly, avoiding subsequent cleaning steps. cleaning substances can severely damage the microphone MEMS element.
- 6. it is recommended to cover the sound port with protective tape during PCB sawing or system assembly. This prevents blocking or partially blocking the acoustic port hole during PCB assembly.
- 7. Do not use excessive force to place the microphone on the PCB. Use industry standard pick and place tools to limit the mechanical force exerted on the package.

Reliability Testing (Samples under test are acclimated at $T_A = 23\pm2^{\circ}$ C, R.H. = $55\pm10\%$ for two hours. After each test completes and corresponding recovery time (if applicable) elapses, any measured sensitivity change is $\leq\pm3$ dB, unless otherwise specified)

Type of Test	
High Temperature Storage Test	1000hrs at 105±3°C
night temperature storage test	Two-hour recovery
Lligh Tomporature Operational	1000hrs at 105±3°C
High Temperature Operational	$V_{DD} = V_{DD}$ (max)
Test	Four-hour recovery

	1000hrs at -40±3°C
Low Temperature Storage Test	Two-hour recovery
	1000hrs at -40±3°C
Low Temperature Operational	$V_{DD} = V_{DD} \text{ (max)}$
Test	Four-hour recovery
	1000hrs at 85±3°C and 85%RH
High Humidity, High Temperature	$V_{DD} = V_{DD}$ (max)
Operating Test	Twelve-hour recovery
Operating resi	No corrosion or defamation inside the microphone
	168hrs at 65±3°C and 95%RH
High Humidity, High Temperature	$V_{DD} = V_{DD}$ (max)
Operating Test	Twelve-hour recovery
Operating resi	No corrosion or defamation inside the microphone
	Double-case method:
	15min at -40±3°C
Temperature-Cycle, Thermal	Followed by
Shock Test	15min at 125±3°C
	100 cycles, two-hour recovery
	Twelve minutes along the x, y, and z axis
	If $I_{IN} = 20$ Hz to 2kHz
 Vibration Test	20G peak acceleration
VIDIGITOTI TEST	Two-hour recovery
	Less than 1dB sensitivity change
	Height: 1.5m
	Fixture weight: 150±10g
	Fixture's sound hole diameter is ≥0.8mm
Drop Test	Reference surface is marble floor
	Duration: four corners x four times; six faces x four times
	Less than 1dB sensitivity change
Tumble Test	Height: 1.0m
	Fixture weight: 150±10g
	Fixture's sound hole diameter is ≥0.8mm
	Duration: 300 cycles
	Less than 1dB sensitivity change
	Measured according to MIL-STD-883G, Method 3015.7,
ESD Sensitivity	Human Body Model (HBM)
,	Identify ESD threshold levels indicating 3000V HBM passage.
	Air pressure = 0.3MPa
	Distance = 3cm
Air Pressure Test	Time = 10sec
	Air discharge port diameter exceeds microphone's
	acoustic port diameter
	10000G
	Pulse width = 0.1ms
Structure Shock Test	X, Y, and Z axis
	Three times along each axis
	Sensitivity changes less than 1dB

Dimensions (Dimension are in mm.)



Item	Dimension	Tolerance(+/-)	Units
Length(L)	2.75	0.10	mm
Width(W)	1.85	0.10	mm
Height(H)	0.9	0.10	mm
Acoustic Port(AP)	Ø0.25	0.05	mm

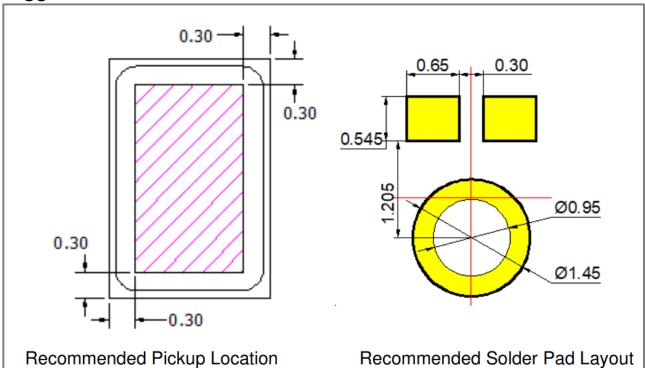
Pin #	Pin Name	Type	Description
1	V_{DD}	Power	Power Supply
2	Output	Signal	Output Signal
3	GND	Ground	Ground

Notes:

All dimensions are in millimeter (mm).

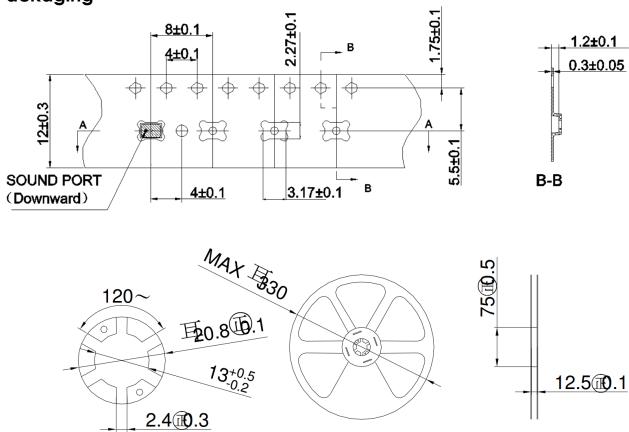
Tolerance±0.15mm unless otherwise specified.

Suggested Land Pattern*

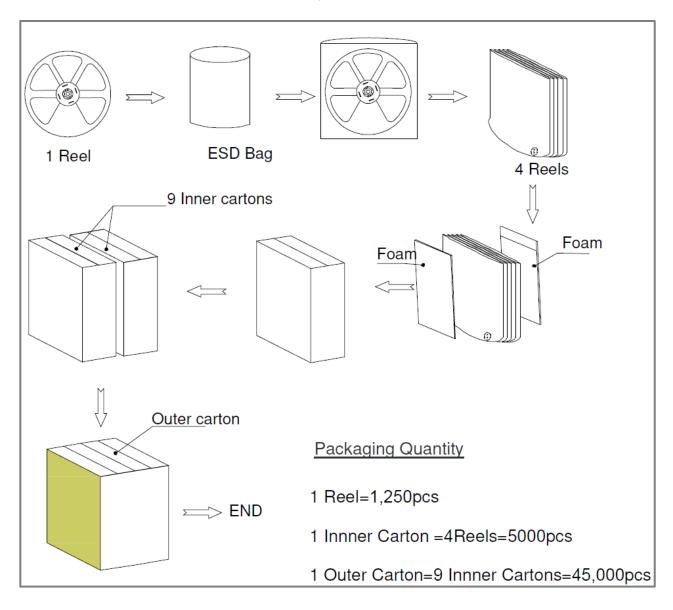


^{*}This land pattern is advisory only and its use or adaptation is entirely voluntary. PUI Audio disclaims all liability of any kind associated with the use, application, or adaptation of this land pattern.

Packaging



All Dimensions are in millimeter (mm).



Specifications Revisions

opcomouncing Revisions		
Revision	Description	Date
Α	Released from Engineering	05-05-2023

Note:

- 1. Unless otherwise specified:
 - A. All dimensions are in millimeters.
 - B. Default tolerances are ± 0.5 mm and angles are $\pm 3^{\circ}$.
- 2. Specifications subject to change or withdrawal without notice.
- 3. This part is ROHS 2015/863/EU compliant.